



COM-HPC[®] SOLUTIONS

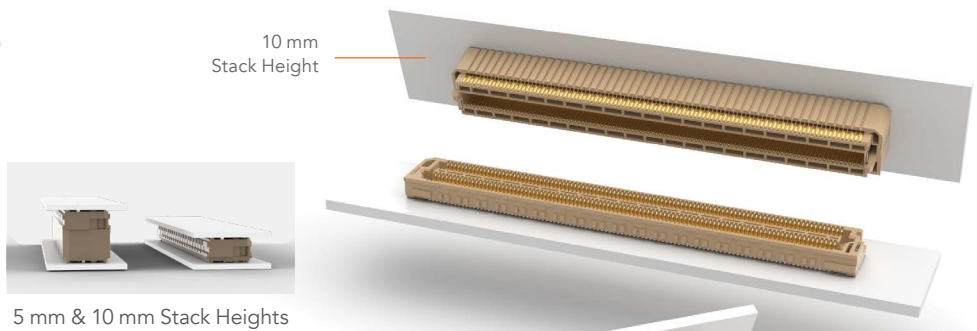
0.635 mm Pitch High-Speed, High-Density System

Samtec offers a high-density interconnect system that meets the COM-HPC[®] standard for high-performance Computer-On-Modules. COM-HPC[®] meets the growing demands for embedded systems to provide ultra-high speed performance and extended connectivity with limitless scalability.



HIGH-SPEED PERFORMANCE

- Up to 32 Gbps per channel
 - 4096 Gbps max aggregate
 - 2088 Gbps per square inch
- PCIe[®] 5.0 capable
- 100 Gb (4 x 25 Gb) Ethernet capable
- Up to 300 W at 11.4 – 12.6 Volts

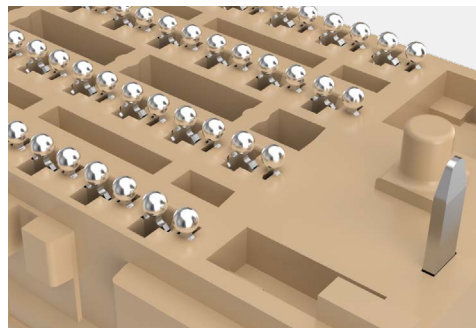


HIGH-DENSITY DESIGN

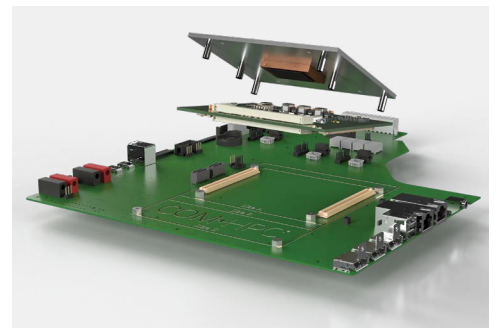
- High pin count interconnect system
 - 400 total pins
 - 4 x 100 design
- 0.635 mm pitch
 - Row 1 to row 2: 2.2 mm
 - Row 2 to row 3: 2.4 mm
 - Row 3 to row 4: 2.2 mm

APPLICATIONS

- Datacom & Telecom
- Embedded Edge Servers
- Industrial
- Medical Imaging
- 5G Wireless Infrastructure
- 5G Connected Vehicles



BGA Mount Increases Density & Performance



Typical COM-HPC[®] Module, Carrier & Heat Sink

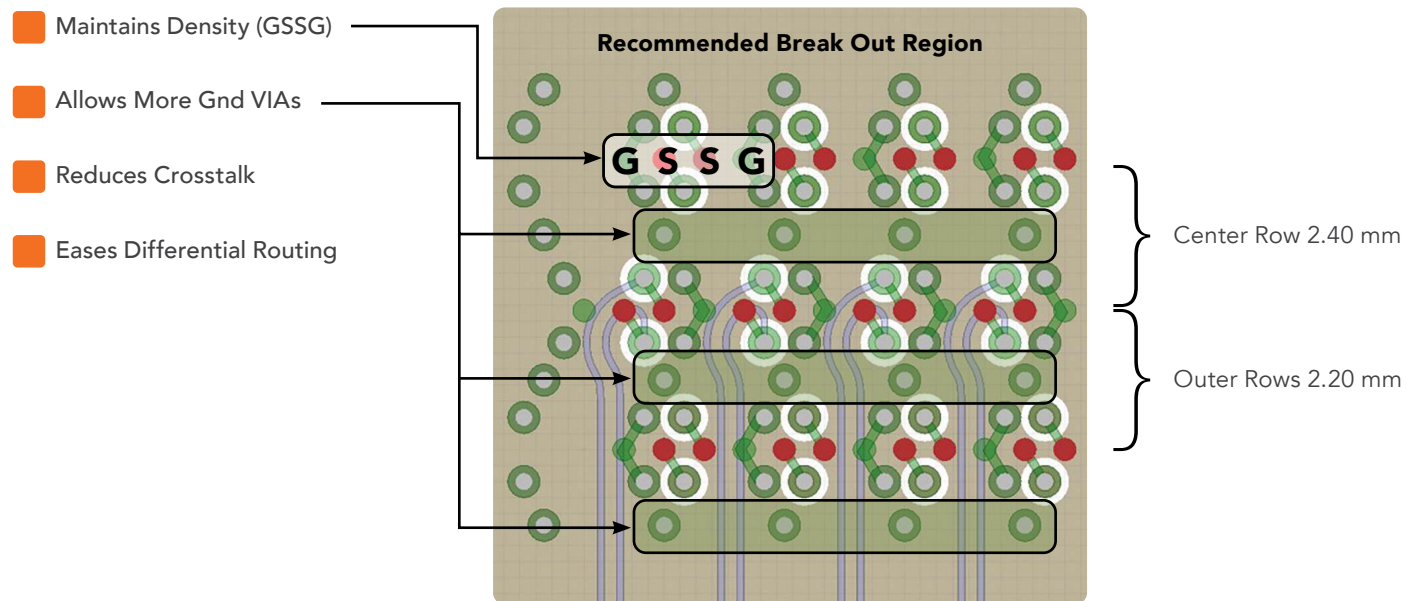
SYSTEM

- ASP-230332-01 (Female) / ASP-230333-01 (Male) - 5 mm Stack Height
- ASP-230332-01 (Female) / ASP-230336-01 (Male) - 10 mm Stack Height
- ASP-222919-01 - 10 mm Stack Micro Jack Screw Precision Board Stacking Standoff

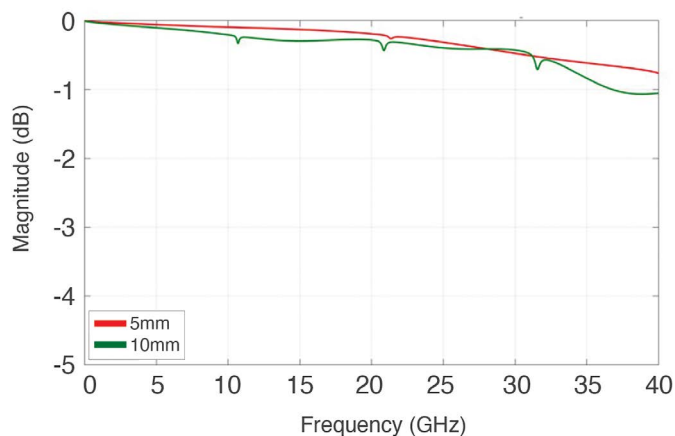
For more information, please visit samtec.com/COMHPC or email COMHPC@samtec.com.

TECHNICAL DATA

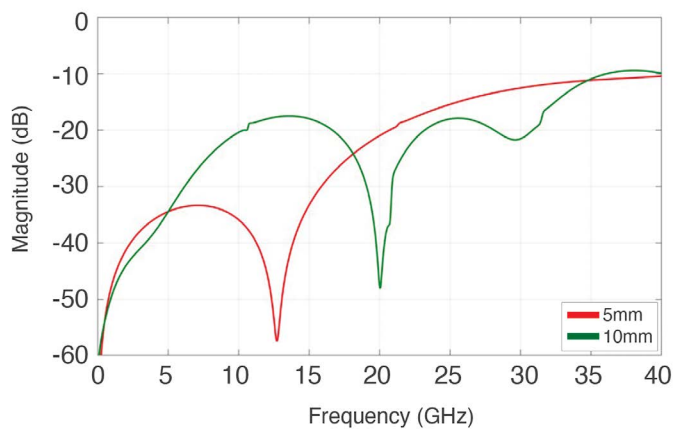
BENEFITS OF INCREASED ROW-TO-ROW SPACING



CONNECTOR-ONLY INSERTION LOSS (IL)



CONNECTOR-ONLY RETURN LOSS (RL)



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